

<u>PS Module prototype</u>

Module prototype discussion

Bits and pieces...

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Module prototype

- Ordered AI-CF (Metgraf 4-230) with dimensions: 12"x5.25"x0.5"
 - Estimated arrival 09/05
 - Cut with "wire EDM"
 - Start with pure AI test structures
- Carbon Fiber sheets: K13C
 - 4 layers a 60 μ m \rightarrow 240 μ m
 - First drawings of the individual by Greg (from today)
- Sensors ready, need to be bump-bonded with RO chips

	Al MetGraf 4-230
Matrix Alloy	Al
TC (W/mK)	
In Plane (x-y)	220-230
Thickness (z)	120
Ср (Ј/g-К)	0.852
CTE (Avg. 20°C to 150°C ppm/C)	
In Plane (x-y)	4
Thickness (z)	24
Tensile Strength (ksi)	
In Plane (x-y)	15
Thickness (z)	
Compressive Strength (ksi)	29.4
Yield Strength (ksi In Comp)	15.9
Young's Modulus (msi)	14.3
Flexure Strength (ksi)	27
Electrical Resistivity (µ·ohm·cm)	
Hardness (Rockwell E)	
Density (g/cc)	2.40
Plating	Ni, Au, Ag
Machinability	Excellent



Module prototype / CERN









 Individual pieces of AI-CF might be easier to machine, but thermal conductivity worse and not as stiff









Module prototype / CERN





Fiber Orientation in the Y-Z plane

Module prototype / FNAL

• PS4 parts made from Carbon Fiber – Sketch by Greg (from today)





Module prototype

- Build a full module prototype based on "CERN" design files Using AI-CF, carbon fiber and sensors + bump-bonded RO chips (with internal heating)
- Add additional heating for the DC-DC converters and other Heat generators on other side of module
- Somewhat different in terms of thickness: 300μm + 600μm(chips)
- Study thermal aspects of the module prototype \rightarrow reference
- <u>Optimize module, some ideas:</u>
 - one AI-CF structure instead of many pieces
 - Avoid gaps, better thermal connectivity
 - Carbon foam instead of AI-CF



• Al-CF design (one structure) by Marvin



Module prototype / FNAL

- AI-CF design (one structure) by Marvin
- Better thermal conductivity, stiffer test thermal properties of this alternative design as well



Rod support structure

Rod support structure:

- Start from ATLAS IBL and "match" it to CMS dimensions/needs
- Carbon Fiber base plate with carbon foam around cooling pipe and honey comb for most of the bulk





Adhesive tests

- Has putting the phase change adhesive on silicon an effect on its properties ?
 - Check via taking IC curves at room temp for reference
 - Put Laird TCPM 583 on one, check again at room temp
 - Heat over night to 80 deg C and take IV curve again





•Check via taking IC curves at room temp for reference

IV curves - non heated

IV curves non heated





• Put Laird TCPM 583 on one, check again at room temp

IV curves - non heated





Put Laird TCPM 583 on one, check again at room temp
Heat over night to 80 deg C and take IV curve again

IV curves heated



 Heating has an effect, TCPM not ? --> can repeat tests with other silicon as well



• Silicon in controlled environment, boxed & sealed





- Same model for 2D and 3D analysis
- Material properties and geometry stored in an Excel file
 - 2D and 3D use different files
- Application program is used to create the model
 - 2D and 3D have different programs



- Models are compared to "quarter sensor", use 1/4 of nominal heat load: 1.25 W
- Heat load divided by number of surface nodes, result is assigned as heating power to each surface node







- Differences with respect to averaged Tube in/out (-20C)
 - "Sim Δ T" taken from model described earlier
 - Similar but larger difference in the data from end to mid
 - Old and new data are different at edges ("q98")



- Differences with respect to averaged Tube in/out (-20C) as a function of heating power
- "Sim Δ T" taken from model described earlier
- Three sets: "98 98mm (across)", "83 83mm (across)" and mid-edge "98 53mm"
- More pronounced "edge" in data compared to sim (green)

CMS detector upgrade



Temperature sensors:

"c 1.5": center line 1.5mm from edge "c 18": center line 18mm from edge, etc

"q 1.5": quarter line 69mm from edge, etc







Temperature at silicon midline